



## AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 1 line 3 with the following amended paragraph marked up to show changes made relative to the immediate prior version:

The present application is related to commonly-assigned and co-pending U.S. Patent Application No. 10/003,238[[ (Attorney Docket No. P12099) ]], entitled ELECTRONIC ASSEMBLY WITH FILLED NO-FLOW UNDERFILL AND METHODS OF MANUFACTURE and filed on October 26, 2001[[ \_\_\_\_\_ ]], and U.S. Patent Application No. 10/403,755[[ (Attorney Docket No. P15835) ]], entitled TEMPERATURE SUSTAINING FLIP CHIP ASSEMBLY PROCESS and filed on March 31, 2003[[ \_\_\_\_\_ ]].